

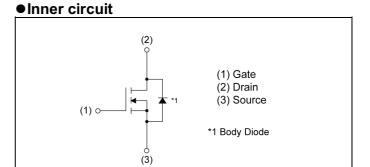
Nch 650V 9A Power MOSFET

V _{DSS}	650V
R _{DS(on)} (Max.)	0.585Ω
I _D	±9A
P _D	94W

● Outline

Features

- 1) Low on-resistance
- 2) Ultra fast switching speed
- 3) Parallel use is easy
- 4) Pb-free plating; RoHS compliant



(2)

Application

Switching

Packaging specifications

Packing	Embossed Tape
Packing code	TL
Marking	R6509KNJ
Basic ordering unit (pcs)	1000

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V _{DSS}	650	V
Continuous drain current (T _c = 25°C)		I _D *1	±9	Α
Pulsed drain current		I _{DP} *2	±27	Α
Coto Course valters	static	V	±20	V
Gate - Source voltage	AC(f>1Hz)	V_GSS	±30	V
Avalanche current, single pulse		I _{AS}	1.4	Α
Avalanche energy, single pulse		E _{AS} *3	158	mJ
Power dissipation (T _c = 25°C)	P _D	94	W	
Junction temperature	T _j	150	°C	
Operating junction and storage tempera	ature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Downwortow	Cymah al	Values			1.1:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *4	-	-	1.3	°C/W
Thermal resistance, junction - ambient	R _{thJA} *5	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

● Electrical characteristics (T_a = 25°C)

Parameter	Cumb al	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = 1mA$	650	-	-	V
		$V_{DS} = 650V, V_{GS} = 0V$				
Zero gate voltage drain current	I _{DSS}	$T_j = 25^{\circ}C$	-	-	100	μΑ
		$T_j = 125^{\circ}C$	1	-	1000	
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	1	-	±100	nA
Gate threshold voltage V _G		$V_{DS} = V_{GS}, I_{D} = 230 \mu A$	3	-	5	V
		$V_{GS} = 10V, I_D = 2.8A$				
Static drain - source on - state resistance	R _{DS(on)} *6	$T_j = 25^{\circ}C$	-	0.530	0.585	Ω
		$T_j = 125^{\circ}C$	1	-	1	
Gate resistance	R_{G}	f = 1MHz, open drain	-	3.1	-	Ω

● Electrical characteristics (T_a = 25°C)

Davamatar	Cymah al	Conditions		Unit			
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Urill	
Input capacitance	pacitance C _{iss}		-	540	-		
Output capacitance C _{oss}		V _{DS} = 25V	-	550	-	pF	
Reverse transfer capacitance C _{rss}		f = 1MHz	-	25	-		
Turn - on delay time	t _{d(on)} *6	$V_{DD} \simeq 300V$, $V_{GS} = 10V$	-	20	-		
Rise time	t _r *6	I _D = 4.5A	-	20	-		
Turn - off delay time $t_{d(off)}^{*6}$		$R_L \simeq 66.7\Omega$	-	38	-	ns	
Fall time	t _f *6	$R_G = 10\Omega$	-	20	-		

● Gate charge characteristics (T_a = 25°C)

Darameter	Cymabal	Conditions	Values			Lloit
Parameter	Symbol	nbol Conditions		Тур.	Max.	Unit
Total gate charge	Q_g^{*6}	V _{DD} ≈ 300V	-	16.5	-	
Gate - Source charge	Q _{gs} *6	I _D = 9A	-	4.5	-	nC
Gate - Drain charge	Q _{gd} *6	V _{GS} = 10V	-	7.6	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 300V$, $I_D = 9.0A$	-	6.9	-	V

^{*1} Limited only by maximum channel temperature allowed.

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L \doteqdot 100mH, V_{DD}=50V, R_G=25 Ω , STARTING T_i=25 $^{\circ}$ C

^{*4} T_C=25°C

^{*5} Mounted on an epoxy PCB FR4 (25mm x 27mm x 0.8mm)

^{*6} Pulsed

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Source current	I _S *1	T _C = 25°C	1	-	9	Α
Pulsed source current	I _{SP} *2	1C - 23 C	1	-	27	Α
Source-Drain voltage	V _{SD} *6	$V_{GS} = 0V, I_{S} = 9.0A$	-	-	1.5	V
Reverse recovery time	t _{rr} *6		-	360	-	ns
Reverse recovery charge Q_{rr}^{*6} $I_S = 9A$ $di/dt = 100A/\mu s$		-	3.6	-	μC	
Peak reverse recovery current	_{rr} *6		-	20	-	Α

Fig.1 Power Dissipation Derating Curve

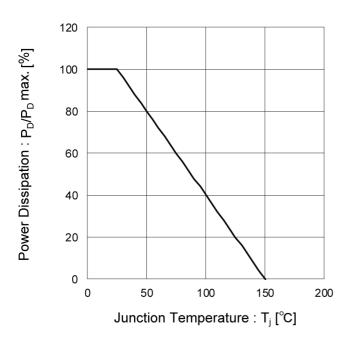


Fig.2 Drain Current Derating Curve

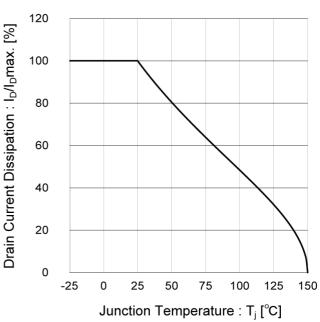


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

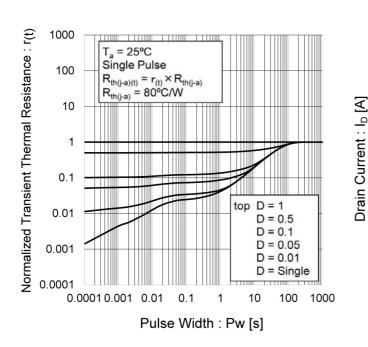


Fig.4 Maximum Safe Operating Area

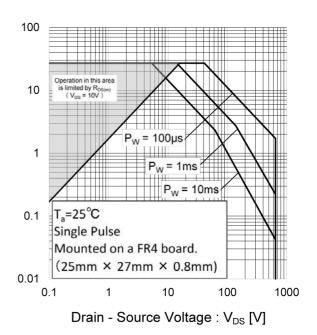


Fig.5 Avalanche Energy Derating
Curve vs. Junction Temperature

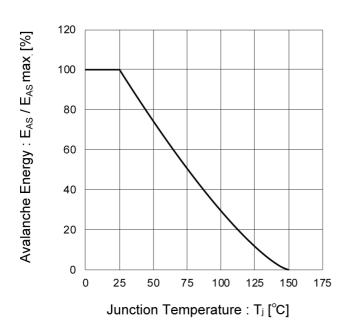


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

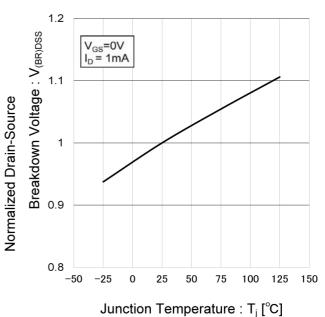


Fig.7 Typical Output Characteristics(I)

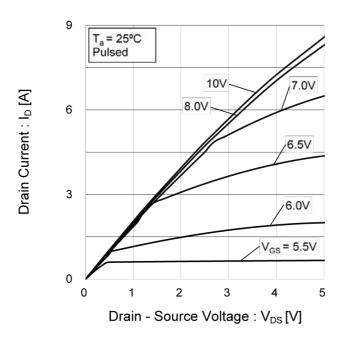
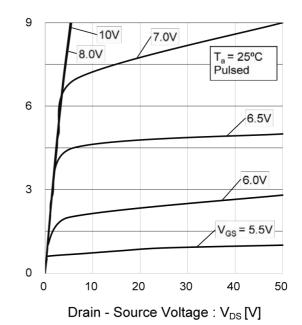


Fig.8 Typical Output Characteristics(II)



Drain Current : I_D [A]

Fig.9 Typical Transfer Characteristics

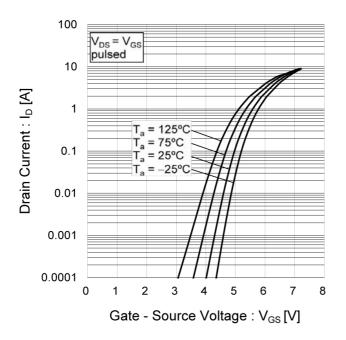


Fig.10 Normalized Gate Threshold .

Voltage vs Junction Temperature

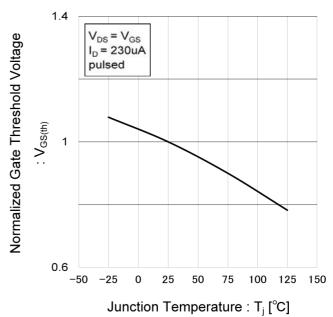


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

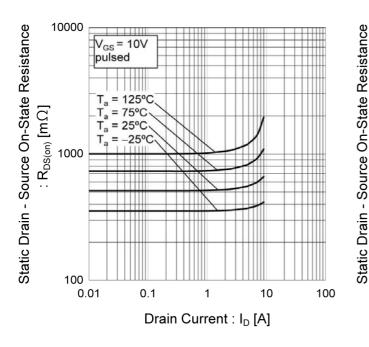


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

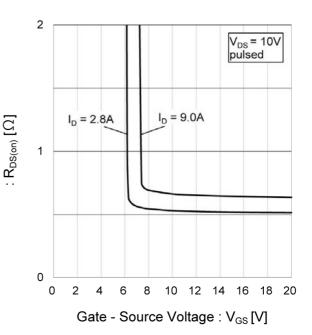


Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

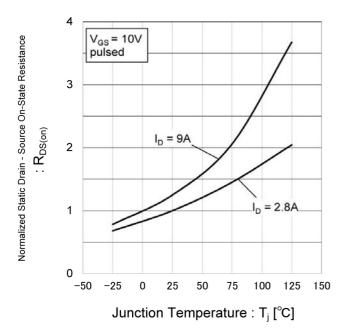


Fig.14 Typical Capacitance vs.

Drain - Source Voltage

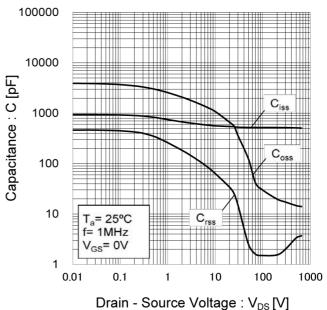


Fig.15 Switching Characteristics

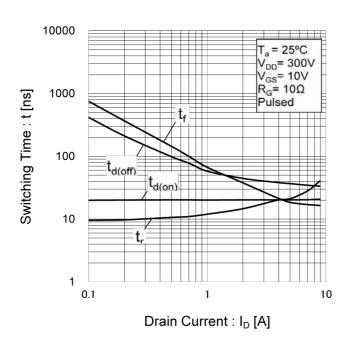
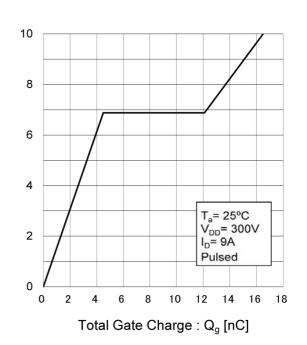


Fig.16 Typical Gate Charge



Gate - Source Voltage : V_{GS} [V]

Fig.17 Source Current vs. Source - Drain Voltage

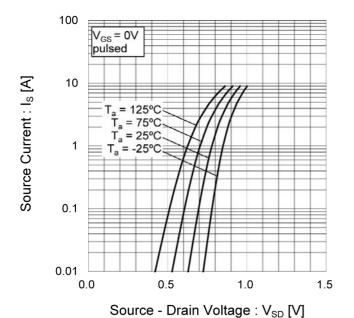
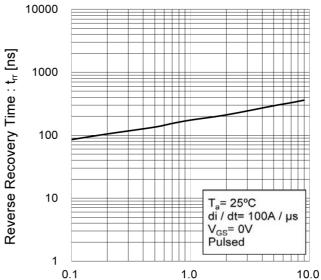


Fig.18 Reverse Recovery Time vs.
Inverse Diode Forward Current



Inverse Diode Forward Current : I_S [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

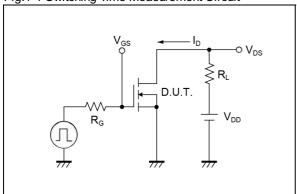


Fig.2-1 Gate Charge Measurement Circuit

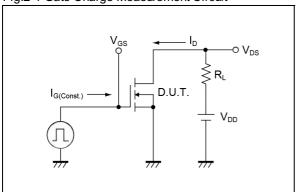


Fig.3-1 Avalanche Measurement Circuit

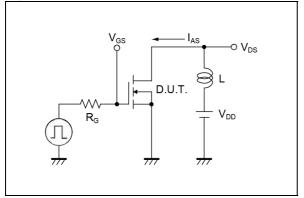


Fig.4-1 trr Measurement Circuit

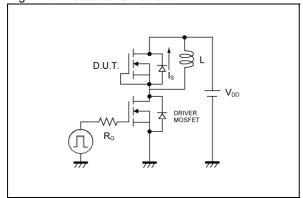


Fig.1-2 Switching Waveforms

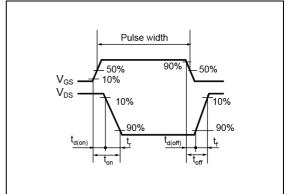


Fig.2-2 Gate Charge Waveform

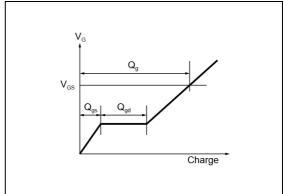


Fig.3-2 Avalanche Waveform

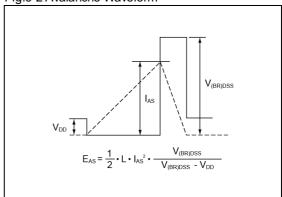
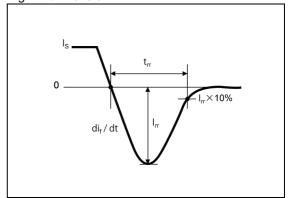
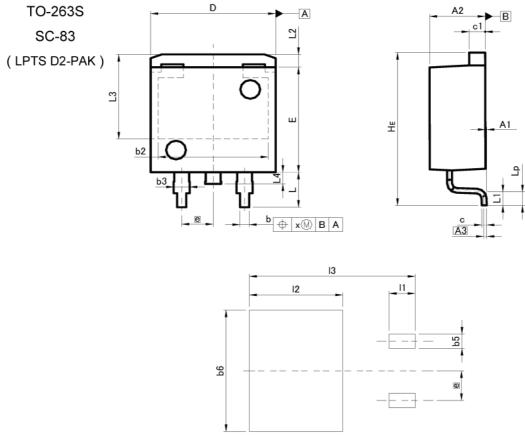


Fig.4-2 trr Waveform



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.:	25	0.0	10
b	0.68	0.98	0.027	0.039
b2	8.9	90	0.3	50
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.100	
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.130
L1	1.	1.20		147
L2	1.	1.10		43
L3	7.:	25	0.285	
L4	1.0	00	0.0	39
Lp	0.90	1.50	0.035	0.059
Х	= = =	0.25	= 1	0.010
	MILIM	FTERS	INC	HES
DIM H	IVITETIVII	- I LINO	IIVO	ILO TATAL

MAX

MAX 0.049 1.23 10.40 0.409 0.083 2.10 7.55 13.40

MIN

Dimension in mm/inches

MIN



DIM

bb

b6

11 12 13

Notice

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CLASSⅢ	CL ACCTI	CLASS II b	CLASSⅢ
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSIII

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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